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4-bit Parallel Access Shift Register



ADE-205-431 (Z) 1st. Edition Sep. 2000

Description

This 4-bit register features parallel and serial inputs, parallel outputs, mode control, and two clock inputs. The register has three mode operation:

- Parallel (broadside) load
- Shift right (the direction Q_A toward Q_D)
- Shift left (the direction Q_D toward Q_A)

Parallel loading is accomplished by applying the four bits of data and taking the mode conrol input high. The data is loaded into the associated flip-flops and appears at the outputs after the high-to-low transition of the clock-2 input. During loading, the entry of serial data is inhibited. Shift right is accomplished on the high-to-low transition of clock-1 when the mode control is low; shift left is accomplished on the high-to-low transition of clock-2 when the mode control is high by connecting the output of each flip-flop (Q_D to input C, etc.) and serial data is entered at input D. The clock input may be applied commonly to clock-1 and clock-2 if both modes can be clocked from the same source. Changes at the mode control input should normally be made while both clock inputs are low: however, conditions described in the last three lines of the function table will also ensure that register contents are protected.

Features

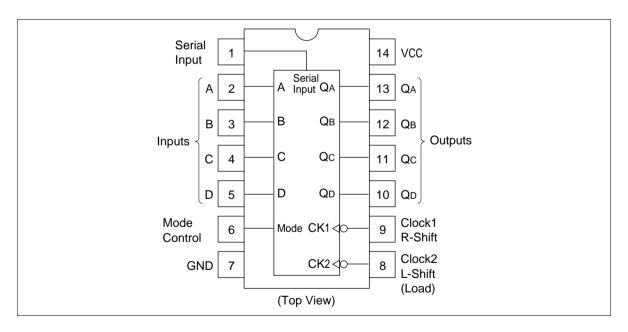
- High Speed Operation: t_{pd} (Clock to Q) = 17 ns typ ($C_L = 50 \text{ pF}$)
- High Output Current: Fanout of 10 LSTTL Loads
- Wide Operating Voltage: $V_{CC} = 2$ to 6 V
- Low Input Current: 1 μA max
- Low Quiescent Supply Current: I_{CC} (static) = 4 μ A max (Ta = 25°C)

Function Table

Inputs

Clocks			Paral	lel			Outpu	Outputs			
Mode Control	2 (L)	1 (R)	Serial	Α	В	С	D	Q _A	$\mathbf{Q}_{\scriptscriptstyle B}$	\mathbf{Q}_{c}	\mathbf{Q}_{D}
Н	Н	Х	Х	Х	Х	Х	Х	Q _{A0}	$Q_{_{B0}}$	Q_{c0}	Q_{D0}
Н		Х	Х	а	b	С	d	а	b	С	d
Н		Х	Х	Q_{B}	Q_{C}	Q_{D}	d	\boldsymbol{Q}_{Bn}	Q_{Cn}	Q_{Dn}	d
L	L	Н	Х	Х	Х	Х	Х	Q _{A0}	Q_{B0}	Q_{c0}	Q_{D0}
L	Х		Н	Х	Х	Х	Х	Н	Q_{An}	Q_{Bn}	\boldsymbol{Q}_{Cn}
L	Х		L	Х	Х	Х	Х	L	\mathbf{Q}_{An}	\boldsymbol{Q}_{Bn}	\boldsymbol{Q}_{Cn}
	L	L	Х	Х	Х	Х	Х	Q_{A0}	Q_{B0}	Q_{co}	Q_{D0}
_	L	L	Х	Х	Х	Х	Х	Q_{A0}	$Q_{_{B0}}$	Q_{c0}	Q_{D0}
	L	Н	Х	Х	Х	Х	Х	Q_{A0}	Q_{B0}	Q_{c0}	Q_{D0}
	Н	L	Х	Х	Х	Х	Х	Q_{A0}	Q_{B0}	Q_{c0}	Q_{D0}
	Н	Н	Х	Х	Х	Х	Х	Q_{A0}	Q_{B0}	Q_{co}	Q_{D0}

Pin Arrangement



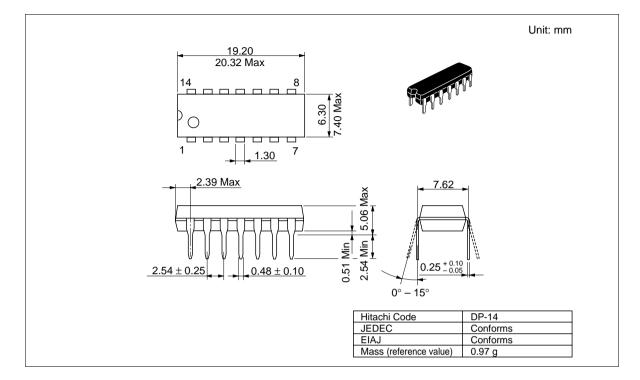
DC Characteristics

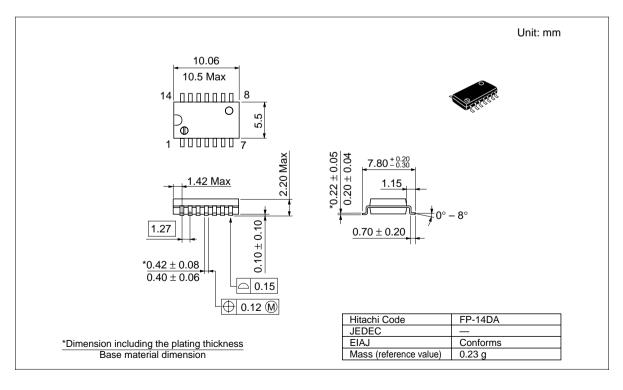
			Ta =	: 25°C		Ta = - +85°C	–40 to C			
Item	Symbol	V _{cc} (V)	Min	Тур	Max	Min	Max	Unit	Test Condition	าร
Input voltage	V _{IH}	2.0	1.5			1.5	_	V		
		4.5	3.15	—	—	3.15	—			
		6.0	4.2		—	4.2	—	_		
	V _{IL}	2.0			0.5	—	0.5	V		
		4.5		_	1.35	_	1.35	_		
		6.0	_	_	1.8	_	1.8	_		
Output voltage	V _{OH}	2.0	1.9	2.0	_	1.9	_	V	$Vin = V_{IH} \text{ or } V_{IL}$	I _{OH} = -20 μA
		4.5	4.4	4.5	_	4.4	_	_		
		6.0	5.9	6.0	—	5.9	—	_		
		4.5	4.18			4.13	—	_		$I_{OH} = -4 \text{ mA}$
		6.0	5.68		_	5.63	_	_		I _{он} = -5.2 mA
	V _{OL}	2.0		0.0	0.1	—	0.1	V	$Vin = V_{IH} \text{ or } V_{IL}$	$I_{OL} = 20 \ \mu A$
		4.5		0.0	0.1	—	0.1	_		
		6.0	_	0.0	0.1	_	0.1	_		
		4.5			0.26		0.33	_		$I_{OL} = 4 \text{ mA}$
		6.0			0.26		0.33	_		I _{oL} = 5.2 mA
Input current	lin	6.0	_	_	±0.1	_	±1.0	μΑ	$Vin = V_{CC} \text{ or } GN$	ND
Quiescent supply current	I _{cc}	6.0		—	4.0	—	40	μΑ	Vin = V _{cc} or GN	ND, lout = 0 μA

AC Characteristics ($C_L = 50 \text{ pF}$, Input $t_r = t_f = 6 \text{ ns}$)

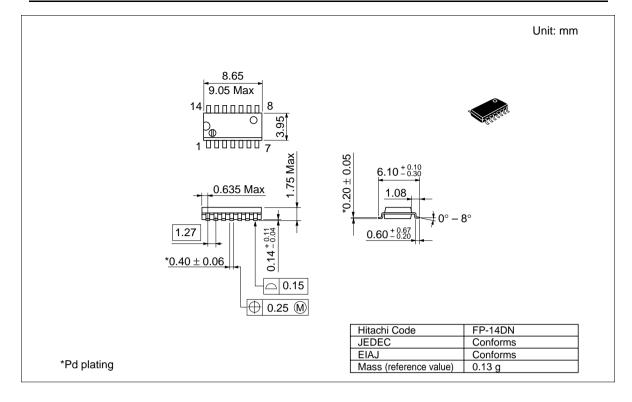
			Ta =	: 25°C	;	Ta = - +85°C	-40 to		
ltem	Symbol	V_{cc} (V)	Min	Тур	Max	Min	Max	Unit	Test Conditions
Maximum clock	f_{max}	2.0	_	_	4	_	3	MHz	
frequency		4.5	_	—	20	_	16	_	
		6.0	—	—	24	—	19		
Propagation delay	t _{PLH}	2.0	_	—	145	_	180	ns	
time		4.5	—	17	29	—	36		
		6.0	_	—	25	—	31	_	
	t _{PHL}	2.0	_	_	170	—	215	ns	
		4.5	_	17	34	—	43	_	
		6.0		_	29	—	37	_	
Pulse width	t _w	2.0	80	_		100	_	ns	Clock
		4.5	16	6		20	_	-	
		6.0	14	_		17	_	_	
Setup time	t _{su}	2.0	100	_	_	125	—	ns	
		4.5	20	2	_	25	_	_	
		6.0	17	_		21	_	_	
Hold time	t _h	2.0	10	_	_	10	_	ns	
		4.5	10	-1		10	_	_	
		6.0	10	_	_	10	_	=	
Output rise/fall	t _{TLH}	2.0	_	—	75	_	95	ns	
time	t _{THL}	4.5	_	5	15	_	19	-	
		6.0	_	_	13	_	16	-	
Input capacitance	Cin			5	10		10	pF	

Package Dimensions









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